



# **MULTILAYER CHIP VARISTOR**

For Surge Protection

Size 0603

**VZ0603 Green Material Series** 

\*Contents in this sheet are subject to change without prior notice.

Walsin Multilayer Chip Varistor is a family of Transient Voltage Surge Suppression products.Today, electronic circuits are becoming smaller and more sentive to external interference. Walsin Multilayer Chip Varistor is designed to protect components from destruction of transients and ESD(Electronic Static Discharge). The wide operating voltage and energy rage make Walsin Multilayer Chip Varistor suitable for numerous applications on I/O protection, Vcc protection, Keyboard protection, LCD protection, Sensor protection...etc. The Walsin Chip Varistor is manufactured by Multilayer fabrication technology providing excellent voltage clamping ability and is supplied in leadless, surface mount form, compatible with modern reflow and wave soldering procedures.

## FEATURES

- 1. Multilayer fabrication technology
- 2.  $-40^{\circ}$ C to  $125^{\circ}$ C operating temperature Range
- 3. Operating voltage range  $V_{M(DC)}$  at 5.5V ~ 38V
- 4. Able to withstand ESD test of IEC-61000-4-2
- 5. Bi-directional clamping characteristic

## APPLICATIONS

- 1. Protection of cellular phones, PDA, High Speed Data Line...etc.
- ESD Protection for components sensitive to IEC 61000-4-2, Provides Circuit Board Transient Voltage Protection for Transistors.
- 3. Protection of Video & Audio Ports.

Figure	Symbol	VZ0603 Series
Ts	L	1.60 ± 0.15 mm
	W	0.80 ± 0.15 mm
$\downarrow$ $\downarrow$ $\downarrow$ $T_s$ $\downarrow$ $T_s$	т	0.90 mm (max.)
Wasin	Ts	0.30 ± 0.20 mm

## DIMENSIONS

\*Terminal electrode : Ni / Sn electrode

## **DEVICE RATING AND SPECIFICATIONS**

	MAXIMUM RATINGS					SPECIFICATIONS		
	Max. Continuous Working Voltage		Maximum Non- Repetitive Surge Current	Maximum Non- Repetitive Surge Energy	Max. Claming Voltage at Specified	Nominal Voltage		Typical Capacitance
Part Number	WORKING	y vonage	(8/20 µ s)	(10/1000 µ s)	Current (8/20 μ s)	At IIIA (	(DC) Current @1KHz	
	V <sub>M(DC)</sub>	V <sub>M(AC)</sub>	I <sub>TM</sub>	W <sub>TM</sub>	Vc	$V_{N(DC)}Min$	V <sub>N(DC)</sub> Max.	С
	(V)	(V)	(A)	(J)	(V)	(V)	(V)	(pF)
VZ0603M050AGTN	5.5	4	30	0.1	24 at 1A	8	18	270
VZ0603M090AGTN	9	6	30	0.1	41 at 1A	11.5	21.5	210
VZ0603M180AGTN	18	14	30	0.1	54 at 1A	23	33	150
VZ0603M260AGTN	26	20	30	0.1	70 at 1A	32	42	100
VZ0603M120AGTN	12	-	-	-	110 at 1A	25	40	40
VZ0603M12LAGTN	12	-	-	-	150 at 1A	45	65	3.5
VZ0603M26LAGTN	26	-	-	-	145 at 1A	45	65	4

# STANDARD TESTING CONDITION

Unless otherwise specified

- Temperature : 15 ~ 35°C
- Humidity : 25%RH ~ 85%RH
- Atmospheric pressure : 86kPa ~ 106kPa



# SPECIFICATION

#### 1. Electrical Reliability

Test item	Test condition / Test method	Specification
High temperature storage	+125±3℃ for 1000 hours Measurement to be made after keeping at room temp. for 24 ±2hr	riangleV at 1mA $<$ 10%
Low temperature storage	-40±3℃ for 1000 hours Measurement to be made after keeping at room temp. for 24 ±2h	riangleV at 1mA $<$ 10%
Humidity storage	$40\pm2^\circ\!{\rm C}$ , 90 ~95%RH for 500 hours Measurement to be made after keeping at room temp. for 24 $\pm2h$	riangleV at 1mA $<$ 10%
Temperature cycles	Times : 5 cyclesStepTemp.( $^{\circ}$ C)Time(min.)1-55±330±32room temp.2~33+125±3 $^{\circ}$ C30±24room temp.2~3Measurement to be made after keeping axt room temp. for 24 ±2h	riangle V at 1mA $<$ 10%

#### 2. Mechanical Reliability

Test item	Test condition / Test method	Specification
Solderability	Solder temp. : 230±5°C Immersion time : 2±0.5 sec Immersion and emersion rates : 25mm/s	Min 90% electrode shall be covered with solder.
Resistance to Soldering Heat	Pre-heating : 120~ 150 $^{\circ}$ C , 60 sec Solder temp. : 260±5 $^{\circ}$ C Immersion time : 10±1 sec Measurement to be made after keeping at room temp. for 24 ±2h	∆V at 1mA < 10% Disappearance of electrode due to immersion into solder shall not exceed 25% of edges of each electrode.
Adhesive Strength of Termination	Solder chip on PCB and applied 0805/1206 Series: 10N(1Kgf) for 10 sec 0402/0603 Series: 5N(0.5Kgf) for 10 sec Chip varistor	No visible damage
Vibration	Solder chip on PCB. Frequency : 10 Hz $\sim$ 55 Hz $\sim$ 10 Hz (1min) Oscillation amplitude : 1.5 mm Times : 2 hrs in each of three perpendicular direction	No visible damage
Bending Test	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of 1mm per second until the deflection becomes 1 mm and then the pressure shall be maintained for 5 sec	No visible damage $ riangle V$ at 1mA $<$ 10%

# **SOLDERING CONDITION**

Typical examples of soldering processes that provide reliable joints without any damage are given in figure below:



Infrared soldering profile

## **ORDERING CODE**

VZ	0603	М	050	Α	G	Т	
Type Code	Chip Size	Style	Rated Voltage	Capacitance Tolerance	Termination	Packing	Internal Code
VZ: Walsin Varistor	0402 0603	M: Multilayer A: Array	050 = 5.5V 070 = 7V 090 = 9V 140 = 14V 180 = 18V	A: Standard	G: Green Material	T: Reeled B: Bulk	Blank: None N: New item

# PACKAGING

Paper Tape specifications (unit :mm) and Packaging quantity



Label	А	В	Е	F	ΦD
VZ0603 Series	1.80 ± 0.05	$0.95 \pm 0.05$	1.75 ± 0.05	$3.50 \pm 0.05$	1.55 ± 0.05

Label	P0	P1	Т	W	Quantity/Reel
VZ0603 Series	4.00 ± 0.10	2.00 ± 0.10	0.87 ± 0.05	8.00 ± 0.20	4Kpcs

• Tape Material : Paper tape.

#### **Reel dimensions**



Index	А	В	С
Dimension (mm)	Φ178	Ф60.0	Φ13.5



## CAUTION OF HANDLING

#### Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Traffic signal equipment
- (6) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

#### Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
  - Products should be storage in the warehouse on the following conditions.
  - Temperature : -10 to +40°C
  - Humidity : 30 to 70% relative humidity
  - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
  - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
  - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
  - Products should be storage under the airtight packaged condition.